



PATENTS
112055-0040P1
17732-38560.001

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In Re The Application of:)
David Chong Sook Lim et al.)

Serial No.: 10/664,982)

Examiner: Leonardo Andujar

Filed: September 17, 2003)

Art Unit: 2826

For: PACKAGING SYSTEM FOR)
DIE-UP CONNECTION OF A)
DIE-DOWN ORIENTED INTE-)
GRATED CIRCUIT)

Cesari and McKenna, LLP
88 Black Falcon Avenue
Boston, MA 02210
September 23, 2005

“Express Mail” Mailing-Label Number: EV336699551US

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

SUPPLEMENTAL AMENDMENT

In response to the Office action dated 05/20/2005, please enter the following supplemental amendments: